



AmTECH
MICROELECTRONICS, INC.

Semiconductor Packaging Silicon Valley
(408)-612-8888

ASSEMBLY - STATEMENT OF WORK / RFQ

Fill electronically or print and complete by hand

CUSTOMER & PROJECT INFORMATION

Company:		Date:	
Contact Name:		Project Name & Rev:	
Address:		Description:	
Phone:		Email:	
		*Standard Turn:	
*Expedited Turn Options may be available for an Additional Charge		☐ 3-Day	☐ 5-Day

Quantity of Assemblies: ☐ 1st Article Report Required {FAIR} (additional charge)

PACKAGE / SUBSTRATE

PACKAGE: ☐ Silicon ☐ Glass ☐ LCC ☐ QFN ☐ PGA ☐ DIP
☐ Ceramic Substrate ☐ Flex Substrate ☐ Organic Substrate Other:

Package / Substrate Supplied by: ☐ AmTECH ☐ Customer Desired Package Lead Count:

Lid Supplied by: ☐ Customer ☐ AmTECH

DIE / DIE ATTACH / FLIP CHIP

DIE SIZE: Length: Width: Height: Bond Pad Opening Width: Pad Pitch - Center to Center:

Die surface contact OK? ☐ Yes ☐ No Details:

Die Attach Material: ☐ Non-conductive Epoxy ☐ Conductive epoxy ☐ Solder ☐ Ag Sinter Paste

Other: Solder Material / Alloy:

☐ Flip Chip Bump Alloy: Bump Ht: Bump Pitch: Bump Dia: Underfill:



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WIRE BONDING

Please send now if available. Diagram can be supplied later if this is a budgetary quote.

WIRE BONDING Diagram:

☐ Provided ☐ Will Provide Later

Wire Count:

Bond Wire Type:

☐ Gold (Au) ☐ Aluminum

Bond Wire Size:

☐ 0.8 ☐ 1.0 ☐ 1.2 ☐ 1.3 ☐ 1.5 ☐ 2.0mil Large Diameter Wire:

Bond Type:

☐ Ball Bond ☐ Wedge Bond ☐ Ribbon Bond ☐ Stud Bump

Package Sealing Preference:

☐ Taped Lid (Not for QFN) ☐ Tacked Lid ☐ Sealed Lid ☐ No Lid

Other:

SMT ASSEMBLY & THROUGH-HOLE / PACKAGING CONTINUED

Substrate Size: (L x W x Height / Thickness):

QTY:

Solder Material:

☐ Double Sided Assy ☐ Pb-free Solder

SMT assembly by:

SMDs provided by:

☐ AmTECH ☐ Customer

Parts on Reels? ☐

of Through-hole Parts per Assembly:

of SMDs per Assembly:

Wire Bond Pad Finish:

☐ ENIG ☐ ENEPIG

Other (describe):

Die (Chip) Protection:

☐ UV Glob Top Clear ☐ Glob Top Black ☐ Dam & Fill

Other:

Glob Top (if applicable):

☐ Wires Only ☐ Wires & Chip

Is Plasma Cleaning Acceptable / Is the die sensitive to heat?:

☐ Yes ☐ No If yes, what temp:

☐ PCB cleaning required

Any Special Instructions?

RELIABILITY & FUNCTIONAL TESTING

Reliability Testing:

☐ Wire Pull ☐ Destructive ☐ Non-destructive

Specified limits:

☐ No Testing

☐ Die Shear

☐ Destructive

☐ Non-destructive

Specified limits:

☐ X-Ray

☐ AOI

☐ Measurement

☐ Other

Functional Testing:

☐ None

Test description:

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ADDITIONAL INFORMATION

Additional Info:

AMTECH ENGINEERING NOTES

AmTECH Engineering Notes:

Reviewed By:

Date Reviewed:

AMTECH RFQ PROCESS / DOCUMENTATION CHECKLIST

- ☐ 1. Execute an NDA
- ☐ 2. Define the statement of work and required services.
- ☐ 3. Submit Assembly - Statement of Work / RFQ to AmTECH
- ☐ 4. Provide Required Documentation:
 - ☐ a) Non-Disclosure Agreement (NDA)
 - ☐ b) PowerPoint Presentation / Product Deck
 - ☐ c) PCB Gerber File & Fabrication Drawing
 - ☐ d) Assembly Drawing with Assembly Notes
 - ☐ e) Bill of Materials (BOM) in Excel Format
 - ☐ f) Technical Data Sheets for Key Components
 - ☐ g) 3D CAD Drawing - STEP FILE
 - ☐ h) Die / Flip-Chip Bonding & Wire Bonding Diagram
- ☐ 5. AmTECH provides a quotation.
- ☐ 6. AmTECH performs the requested Manufacturing Services after receipt of PO.

EXTRA NOTES

Use this area for additional project requirements, assumptions, or clarifications.

Extra Notes: